

ABSTRACT OF THE DISCLOSURE

CARRIER AND CMP APPARATUS

5 A carrier and CMP apparatus making the distribution
of pressure applied to the entire surface of the
workpiece, including the outer peripheral portion,
uniform to improve the uniformity of polish of the
entire surface of the workpiece. The carrier 1 is
provided with a housing 10, a carrier base 11, a sheet
10 supporter 13, a hard sheet 18, a soft backing sheet 19,
and a collar 20 and the sheet supporter 13 is formed by
a supporter body 14 having through holes 14a
communicating with the air exit/inlets 11b of the
carrier base 11, a pliable diaphragm 15, and an edge
15 ring 16. Due to this, the force applied to the edge ring
16 of the sheet supporter 13 is relieved by the flexing
of the diaphragm 15 and the air pressure inside the
pressure chamber R applied to the entire surface of the
wafer W is made uniform.

FIGURE 3